

The 25th IEEE Intersociety Conference
on Thermal and Thermomechanical
Phenomena in Electronic Systems
(ITherm 2026)



JW Marriott Orlando
Grande Lakes, Orlando, FL
May 26 – 29, 2026

Sponsors and Exhibitors

LEVEL	PLATINUM	GOLD			SILVER			EXHIBITOR
Event/Category	Conference	WiFi (max 1)	Track	Keynote	Panels	Student Events	Coffee Breaks	
Cost ²	\$7,500	\$5,000			\$2,500			\$3,500
Lanyard branding	<input checked="" type="checkbox"/>							
Exhibitor Booth	8' x 8' (optional)	4' x 8' ³ (optional)						8' x 8'
Standard Conference Registrations ⁴	3	2						1
Booth Staff Registrations ⁵	2	2						2
Pages in Program	2	2			1			1
Organizer Dinner	2	1						
Website, Program and Mobile App Acknowledgement	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>
Event Acknowledgement	Luncheon	WiFi Access	Luncheon	Keynotes	Panels	Student Events	Breaks	
Tote Bag Logo	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>
15min Presentation	<input checked="" type="checkbox"/>							<input checked="" type="checkbox"/>
Coffee Sleeve Branding								sleeves must be provided
Notes	¹ 3D printing and testing suppliers for competition provided Silver Level benefits							
	² 10% discount for first time exhibitors and sponsors							
	³ Booth can be exchanged for one extra student registration (academic institutions)							
	⁴ One standard member/non-member registration can be exchanged for two student registrations							
	⁵ Booth Staff Registrations provides access to breakfast and lunch but not to technical sessions							

Visit the **Sponsors and Exhibitors** webpage below for key dates and registration link
<https://www.ieee-itherm.net/sponsors-and-exhibitors-2026/>

For further information please contact:



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